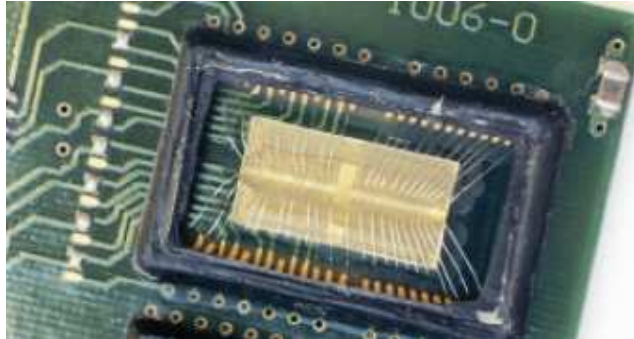


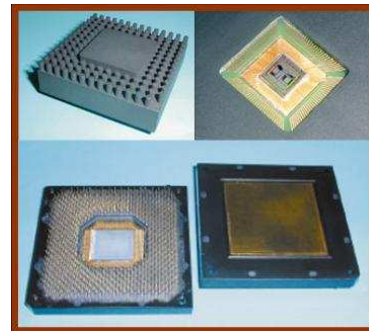
**sep - semiconductor enhanced products**



We offer a wide band of services that enhance the use of semiconductors. Enhancement services include problem-solving engineering and manufacturing for both low and high volume assembly. We refer to our wide variety of products and services as Semiconductor Enhancement Products.

**IC packages**

Design and manufacturing of a broad line of high lead count IC packages utilizing printed circuit board interconnects unique molding capabilities and thermal management solutions.

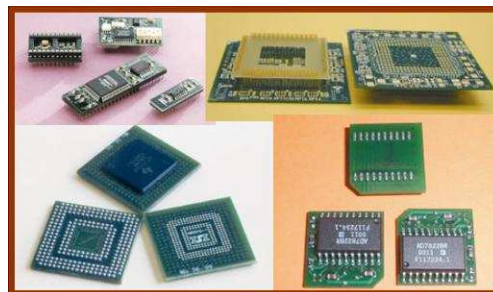


**Chip Modules**

We can help you improve performance and lower cost through design solutions by isolating high performance components on high count multi-layer PCB's that then connect to lower layer count.

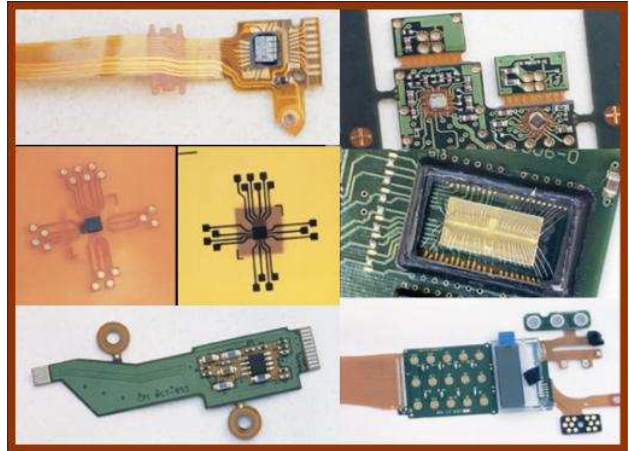
**Footprint Conversion Adapters**

We have produced more than 1,000 adapters that convert one semiconductor form factor to another. Examples: BGA to PGA, BGA to QFP, BGA to BGA, QFP to BGA, SMT to DIP, SMT to SMT, PGA to PGA.



**Chip on Board / Chip on Flex**

Flexible circuit technology is used in discrete packages for improved circuit density. Through the use of unique assembly processes, we can reduce the size and cost of complex circuitry.



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